MA27D270G

Silicon epitaxial planar type

For super high speed switching

Features

- Small reverse current I_R
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- SSS-Mini type 2-pin package

Parameter	Symbol	Rating	Unit			
Reverse voltage	V _R	20	V			
Repetitive peak reverse voltage	V _{RRM}	20	V			
Peak forward current	I_{FM}	200	mA			
Forward current (Average)	I _{F(AV)}	100	mA			
Non-repetitive peak forward surge current *	I _{FSM}	1	А			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings $T_a = 25^{\circ}C$



- Code SSSMini2-F3
- Pin Name 1: Anode
 - 2: Cathode

Marking Symbol: 8L

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

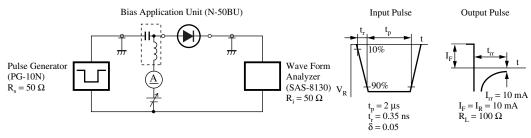
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I _R	$V_R = 10 V$			0.3	μΑ
Forward voltage	V _{F1}	$I_F = 10 \text{ mA}$		0.38	0.44	V
	V _{F2}	$I_F = 100 \text{ mA}$		0.54	0.58	
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		11		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

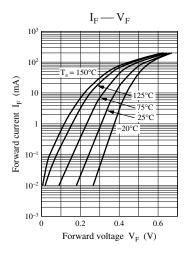
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

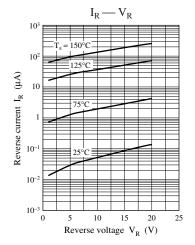
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

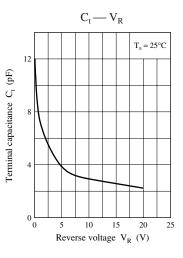
- 3. Rated input/output frequency: 250 MHz
- 4. $*: t_{rr}$ measurement circuit

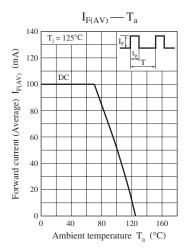


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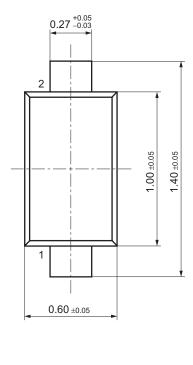


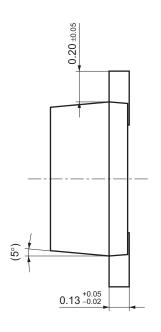


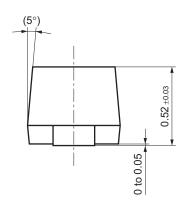


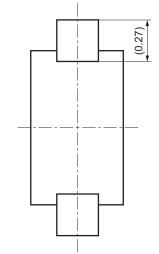
SSSMini2-F3

Unit: mm









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